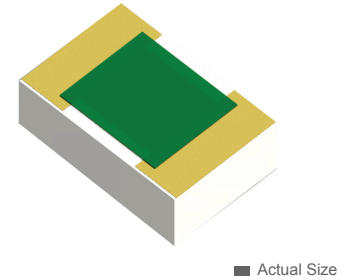


RM0805ZZ-XXXXWN-98 Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)

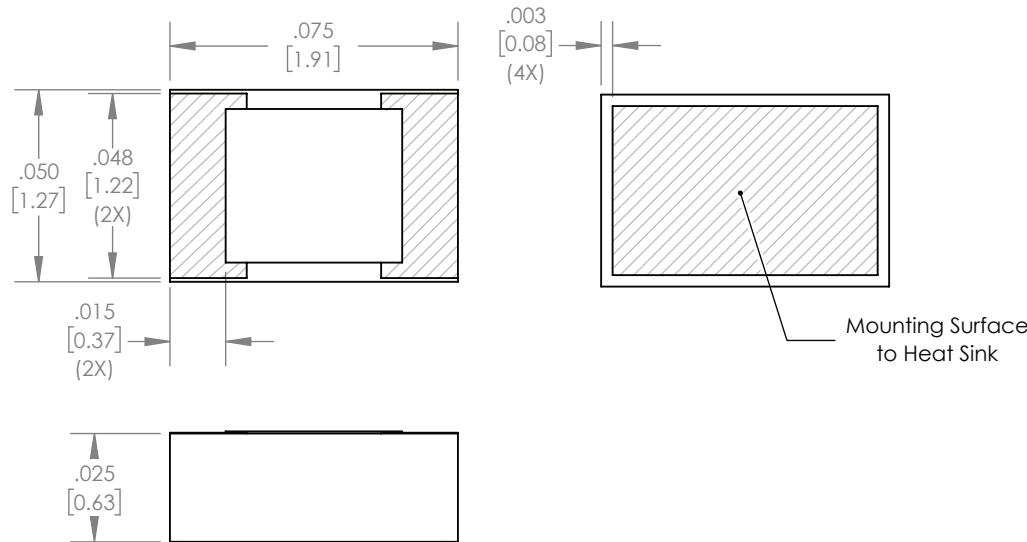
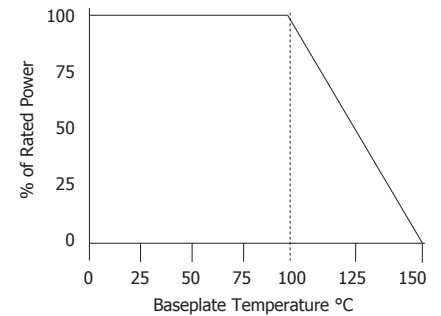


Actual Size

RM0805ZZ-XXXXWN-98 Parameters:

Resistance Range:	0.5Ω - 1MΩ
Rated Power:*	6.25W
Construction:	Thick Film on 0.025" BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM0805ZZ-XXXXWN-98 Dimensions:

**RM0805ZZ-XXXXWN-98
Power Derating Curve**

 Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13]
 unless otherwise stated

Ordering Information:
Example Part Number: RM0805CC-50R0FN-98TR

RM	0805	ZZ	-	XXXX	W	N	-	98	UU
Prefix for Resistor w/ Single-Sided Terminals and Backplane				Value Code	Tolerance	Normal Inspection	Substrate		Packaging
Size	0805			50R0 - 50Ω	F - 1%	Contact factory for additional options	98 - 0.025" BeO		Blank - Bulk
				1000 - 100Ω	G - 2%				WP - Waffle Pack
				1001 - 1KΩ	J - 5%				TR - Tape & Reel

Terminal Metallization

	RoHS	Magnetic	Solder	Epoxy	Wirebond
AS - Tin Lead over Platinum Palladium Gold	No	No	Yes	No	No
CB - Tin Lead over Nickel over Silver	No	Yes	Yes	No	No
CC - 100% Matte Tin over Copper over Silver	Yes	No	Yes	No	No
CT - 100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	No
HA - Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane	Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
JA - Gold over Platinum Palladium Gold	Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RM0805ZZ-XXXXWN-98 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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